

L Number	Hits	Search Text	DB	Time stamp
1	2612713	semiconductor die chip ic (integrated adj circuit) microprocessor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:11
2	698909	((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:12
3	135272	gasket lossy polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
4	1	gasket and lossy and polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
5	6020	((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
6	2231	((esd shielding shielded shield electrostatic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:16
7	763	((heat with (spreader sink metal radiate thermal dissipate dissipative dissipating)) and ((esd shielding shielded shield electrostatic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:22

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4	1	gasket and lossy and polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 16:48
5	6020	(semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
6	2231	(esd shielding shielded shield electrostatic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:16
7	763	(heat with (spreader sink metal radiate thermal dissipate dissipative dissipating)) and ((esd shielding shielded shield electrostatic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:22
8	4594	polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 16:32
9	15	((heat with (spreader sink metal radiate thermal dissipate dissipative dissipating)) and ((esd shielding shielded shield electrostatic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)))) and polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 16:32
10	88	(gasket lossy) same polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 16:48

11	1	(semiconductor die chip ic (integrated adj circuit) microprocessor) same ((gasket lossy) same polytetrafluorethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 16:50
12	8	(semiconductor die chip ic (integrated adj circuit) microprocessor) and ((gasket lossy) same polytetrafluorethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 16:50